ASSOCIATION CONNECTING ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES® international and Par	PC. Bannockl	burn. Illinois. A	Il rights reserved untions.	under both	This docume level parts, t	ent is a declarati the declaration e	on of the su	ibstances v s all lower	vithin the manufac level materials for	turer listed which the	item. Note: manufacture	if the item is an as er has engineering	sembly with low responsibility.	
				Form Type Distribute	e * Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information					tion				
upplier Information														
Company name*	Company uni	Company unique ID			Unique ID Authority				Respo	Response Date*				
onsemi										2023-0	2023-06-08			
Contact Name Title - Contact			ct				Phone - Contact*				Email - Contact*			
Product-Env-Stewards Prod			Product Enviro Compliance			NA				Produ	Product-Env-Stewards@onsemi.com			
Authorized Representative* Ti			Title - Representative			Phone - Representative*				Email	Email - Representative*			
Product-Env-Stewards	Product Enviro Compliance				NA				Produ	Product-Env-Stewards@onsemi.com				
Requester Item Number	quester Item Number Mfr Item		n Number Mfr Item Name			Effective Date	ve Date Version Manufacturing Site			Weight*	UOM	Unit Type		
	FAN311	AN3111ESX Sing. 1A Low Side		ide Drive		2023-06-08		P	РВВ		17.013	mg	Each	
Ianufacturing Proccess Informa	tion						-							
Terminal Plating / Grid Array M	aterial T	ial Terminal Base Alloy J-			L Rating	Peak Process Body Temperature Max Tim			e Max Time at Pe	ık Temper	ature Num	ber of Reflow Cy	eles	
Matte Tin (Sn) - annealed CU Alloy		CU Alloy		1		260		С	30	seco	onds 3			
omments														
vel 1 - maximum time at peak temperat	ure during so	Idering is 10-3	0 seconds											
or more information regarding material	composition	please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		nium (Cr6+), Polybro	ominated Biphenyls (PBB), Polybron	dmium and quantity limit of 0.1% by mass (100 minated Diphenyl Ethers (PBDE), and Bis(2-eth	
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe v others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	ances per the definitio	on above	Supplier Acceptance	* Accepted
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all
Exemption List Version	EL-2011/534/EU				
Declaration Signature					
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the
Supplier Digital Signature Ra	stislav Drska	Le			

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

sigma range of distribution unless otherwise noted).									
Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure	
Die	0.745	mg	Supplier	Silicon (Si)	7440-21-3		0.745	mg	
Die Attach	0.052	mg	Supplier	Ethylene glycol dicyclopentenyl ether methacrylate	68586-19-6		0.0018	mg	
			Supplier	Bis(a,a-dimethylbenzyl) Peroxide	80-43-3		0.0003	mg	
			Supplier	Silver (Ag)	7440-22-4		0.0498	mg	
Lead Frame	7.29	mg	Supplier	Silver (Ag)	7440-22-4		0.008	mg	
			Supplier	Copper (Cu)	7440-50-8		7.282	mg	
Mold Compound-Black	8.4	mg	Supplier	Ortho Cresol Novolac Resin	29690-82-2		2.436	mg	
			Supplier	Carbon Black (C)	1333-86-4		0.084	mg	
			Supplier	Fused Silica (SiO2)	60676-86-0		5.88	mg	
Plating	0.453	mg	Supplier	Tin (Sn)	7440-31-5		0.453	mg	
Wire Bond - Au	0.073	mg	Supplier	Gold (Au)	7440-57-5		0.073	mg	

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 signa range of distribution unless otherwise noted).